SP8J3

Transistors

Switching (-30V, -3.5A)

SP8J3

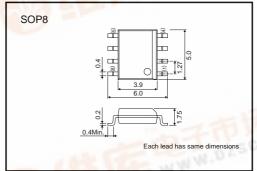
Features

- 1) Low On-resistance. (100m Ω at 4.5V)
- 2) High Power Package.
- 3) High speed switching.
- 4) Low voltage drive. (4.5V)

Applications

Power switching, DC-DC converter

●External dimensions (Unit : mm)



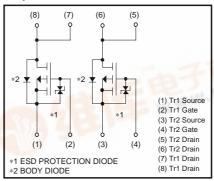
Structure

Silicon P-channel MOS FET

Packaging specifications

	Package	Taping	
Туре	Code	TB	
	Basic ordering unit (pieces)	2500	
SP8J3		0	

Equivalent circuit





● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		V_{DSS}	-30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain august	Continuous	ID	±3.5	Α	
Drain current	Pulsed	I _{DP}	±14	Α *	
Source current	Continuous	Is	-1.6	Α	
(Body diode)	Pulsed	I _{SP}	-14	Α *	
Total power dissipation		P _D	2.0	W *	
Channel temperature		Tch	150	°C	
Range of Storage temperature		Tstg	-55 to +150	°C	
Channel temperature		Tch	150	°C	

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	_	_	±10	μΑ	V _{GS} =±20V, V _{DS} =0V
Drain-source breakdown voltage	V _(BR) DSS	-30	_	_	V	I _D = -1mA, V _G S=0V
Zero gate voltage drain current	IDSS	-	-	-1	μΑ	V _{DS} = -30V, V _{GS} =0V
Gate threshold voltage	V _{GS (th)}	-1.0	_	-2.5	V	V _{DS} = -10V, I _D = -1mA
Otatio Indiana and the		-	65	90	mΩ	I _D = -3.5A, V _G S= -10V *
Static drain-source on-state resistance	RDS (on)	_	100	140	mΩ	I _D = -1.75A, V _G s= -4.5V *
resistance		_	120	165	mΩ	I _D = -1.75A, V _G s= -4.0V *
Forward transfer admittance	Yfs	1.8	_	_	S	V _{DS} = -10V, I _D = -1.75A *
Input capacitance	Ciss	_	490	_	pF	V _{DS} = -10V
Output capacitance	Coss	-	110	_	pF	V _{GS} =0V
Reverse transfer capacitance	Crss	-	75	_	pF	f=1MHz
Turn-on delay time	t _{d (on)}	-	10	_	ns	I _D = -1.75A *
Rise time	tr	-	15	_	ns	V _{DD} = −15V * V _{GS} = −10V
Turn-off delay time	t _{d (off)}	-	35	_	ns	$\begin{array}{c} VGS = -10V \\ RL = 8.6\Omega \end{array}$
Fall time	tf	_	10	_	ns	$R_{GS}=10\Omega$
Total gate charge	Qg	_	5.5	_	nC	V _{DD} ≒−15V
Gate-source charge	Qgs	_	1.5	_	nC	V _{GS} =-5V
Gate-drain charge	Q_{gd}	_	2.0	_	nC	I _D = -3.5A

*Pulsed

Body diode characteristics (source-drain characteristics)

Forward voltage	VSD	_	_	-1.2	V	I _S = -1.6A, V _{GS} =0V



^{*1} Pw≤10μs, Duty cycle≤1% *2 Mounted on a ceramic board

•Electrical characteristic curves

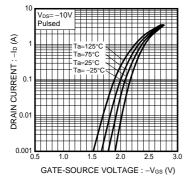


Fig.1 Typical Transfer Characteristics

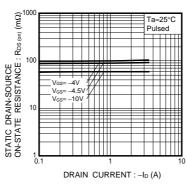


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

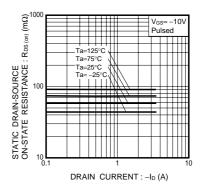


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

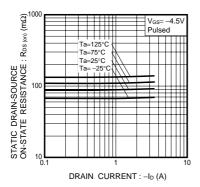


Fig.4 Static Drain-Source On-State vs. Drain Current

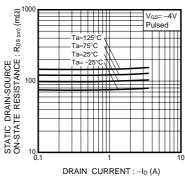


Fig.5 Static Drain-Source On-State vs. Drain Current

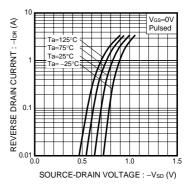


Fig.6 Reverse Drain Current Source-Drain Current

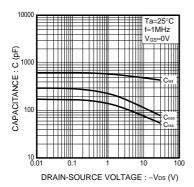


Fig.7 Typical Capacitance vs. Drain-Source Voltage

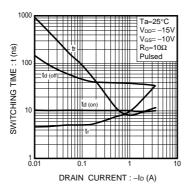


Fig.8 Switching Characteristics

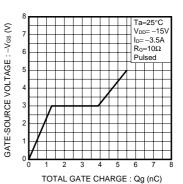


Fig.9 Dynamic Input Characteristics

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Measurement circuits

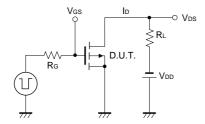


Fig.10 Switching Time Test Circuit

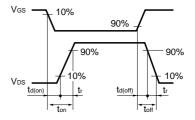


Fig.11 Switching Time Waveforms

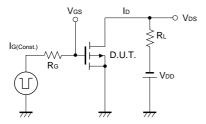


Fig.12 Gate Charge Test Circuit

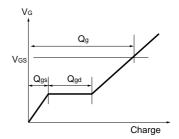


Fig.13 Gate Charge Waveform

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